## **IN THE SPECIFICATION:**

Please insert the following paragraph at page 1, line 4:

## PRIORITY REFERENCE TO PRIOR APPLICATION

This application claims benefit under 35 U.S.C. §119 of Taiwan patent application number 091134865, entitled "LAMINATION PROCESS AND STRUCTURE OF HIGH LAYOUT DENSITY SUBSTRATE," filed on November 29, 2002, by inventors Kwun Yao HO and Moriss KUNG.

2